

12th International Conference on Microwave Materials and their Applications

Call for Papers

Abstract submission open until June 15, 2023 Register under <http://mma2023.uni-mainz.de>

Keynote Speakers



Malgorzata Celuch

President QWED, Warsaw, Poland

**Recent Developments
and Cross-Calibration
of Resonator-Based Techniques
for Microwave
and mmWave Materials Assessment**



Madhavan Swaminathan

Dept. Head Electrical Engineering,
Director, CHIMES (an SRC JUMP 2.0 Center)
Penn State University, PA, USA

**Packaging Materials for Advanced
Computing and Communications -
Challenges and Opportunities**



Yasutaka Sugimoto

Principal Researcher RF development,
Murata Manufacturing, Kyoto, Japan

**LTCC materials
and their processes
for wireless communications**

Conference Topics

- LTCC / ULTCC
- 5G/6G telecommunication
- Material aspects of packaging
- Advances in modelling and characterization
- Microwave and Millimeter-wave materials
- Applications and passive components
- Advances in processing and design
- Green and sustainable materials

Organizers

Martin Letz, SCHOTT AG Mainz
Jure Demsar, JGU Mainz

For further questions and industry exhibition contact:

mma2023@uni-mainz.de

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